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**Mary Ann Maher
Paul J. Resnick**
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Contents

- v Conference Committee
- vii *New optical, acoustic, and electrical diagnostics for the developing world (Plenary Paper) [8251-103]*
S. L. Neale, C. Witte, Y. Bourquin, C. Kremer, A. Menachery, Y. Zhang, R. Wilson, J. Reboud, J. M. Cooper, Univ. of Glasgow (United Kingdom)

PLENARY SESSION

- 8248 02 **Powering the wireless world with MEMS (Plenary Paper) [8248-102]**
S. B. Schaevitz, Lilliputian Systems, Inc. (United States)

SESSION 1 DEVICES AND APPLICATIONS

- 8248 03 **Optically transparent, flexible pressure sensor array micromachined utilizing plasma assisted bonding [8248-01]**
J. Yan, Univ. of California, Davis (United States)
- 8248 04 **Rotary MEMS comb-drive actuator with large deflection for photonic applications [8248-02]**
M. Q. Huda, T. M. F. Amin, Univ. of Alberta (Canada); Y. Ning, G. McKinnon, Norcada Inc. (Canada); J. Tulip, Boreal Laser, Inc. (Canada); W. Jäger, Univ. of Alberta (Canada)
- 8248 05 **Photovoltaic retinal prosthesis for restoring sight to the blind: implant design and fabrication [8248-03]**
L. Wang, Stanford Univ. (United States); K. Mathieson, Stanford Univ. (United States) and Univ. of California, Santa Cruz (United States); T. I. Kamins, J. Loudin, L. Galambos, J. S. Harris, D. Palanker, Stanford Univ. (United States)
- 8248 06 **Micromachined edge illuminated optically transparent automotive light guide panels [8248-04]**
R. A. Ronny, G. K. Knopf, The Univ. of Western Ontario (Canada); E. Bordatchev, M. Tauhiduzzaman, S. Nikumb, National Research Council Canada (Canada)

SESSION 2 MICROSTRUCTURE ENGINEERING

- 8248 07 **Fabrication of microstructures with continuous surface profiles and very large sag heights by laser lithography [8248-06]**
J. Dunkel, Fraunhofer Institute for Applied Optics and Precision Engineering (Germany) and Friedrich-Schiller-Univ. Jena (Germany); F. Wippermann, A. Bräuer, Fraunhofer Institute for Applied Optics and Precision Engineering (Germany)
- 8248 08 **Design of experiment for the optimisation of deep reactive ion etching of silicon inserts for microfabrication [8248-07]**
K. Wallis, C. P. Shaw, J. R. Alcock, Cranfield Univ. (United Kingdom)

- 8248 09 **Impact of initial surface parameters on the final quality of laser micro-polished surfaces** [8248-08]
M. Chow, The Univ. of Western Ontario (Canada); E. V. Bordatchev, National Research Council Canada (Canada); G. K. Knopf, The Univ. of Western Ontario (Canada)

SESSION 3 LASER PROCESSING

- 8248 0C **High aspect ratio microfeatures with laser texturing in mixed ablative-melting regime** [8248-11]
P. M. Romero, N. Otero, A. González, P. Vázquez, Asociación de Investigación Metalúrgica del Noroeste (Spain)
- 8248 0F **Fabrication qualities of micro-gratings encoding dependence on laser parameters by two-beam femtosecond lasers interference** [8248-14]
X. Wang, F. Chen, H. Liu, H. Bian, Q. Yang, J. Si, X. Hou, Xi'an Jiaotong Univ. (China)

SESSION 4 MEMS FABRICATION

- 8248 0G **Bosch-like method for creating high aspect ratio poly(methyl methacrylate) (PMMA) structures** [8248-15]
M. Haiducu, Simon Fraser Univ. (Canada); D. Sameoto, Univ. of Alberta (Canada); I. Foulds, King Abdullah Univ. of Science and Technology (Saudi Arabia); R. W. Johnstone, Teledyne DALSA Semiconductor (Canada); A. M. Parameswaran, Simon Fraser Univ. (Canada)
- 8248 0H **Stress engineering for free-standing SU-8 2002 thin film devices** [8248-16]
K. W. Oliver, S. J. Lukes, M. J. Moghimi, D. L. Dickensheets, Montana State Univ. (United States)
- 8248 0I **Numerical simulation of hot imprint process of periodical lamellar microstructure into polycarbonate** [8248-17]
R. Gaidys, B. Narijauskaitė, A. Palevičius, G. Janušas, Kaunas Univ. of Technology (Lithuania)

POSTER SESSION

- 8248 0J **Electro-hydrodynamic printing using hole-type electrode** [8248-18]
S. Lee, H. Kim, J. Chung, Korea Univ. (Korea, Republic of)
- 8248 0K **Laser-based microstructuring of materials surfaces using low-cost microlens arrays** [8248-19]
D. Nieto, CIDETEC (Spain), National Univ. of Ireland, Galway (Ireland), and Univ. de Santiago de Compostela (Spain); G. Vara, J. A. Diez, CIDETEC (Spain); G. M. O'Connor, National Univ. of Ireland, Galway (Ireland); J. Arines, C. Gómez-Reino, M. Flores-Arias, Univ. de Santiago de Compostela (Spain)

Author Index

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